



Customer Technical Update With LAYTEC



Thursday 12th December 2024 commencing 13:30

TIME	TOPIC	PRESENTER
10 min	Welcome, Introduction Company Overview <ul style="list-style-type: none">Corporate Organization and Oxford Instruments Plasma Technology.Workshop objective.	Gohda-san - Oxford Instruments
30 min	InP and GaAs lasers – III-V Material Processing <ul style="list-style-type: none">Production solution for etching of InP transceivers and GaAs VCSEL.Etch III-V etching process overview for R&D.	Dr Ligang Deng - Oxford Instruments
30 min	SiC PE – Material Processing <ul style="list-style-type: none">Plasma etch and deposition solutions for current and next generation SiC power devices.SiC substrate Epi ready cost reduction for 150mm and 200mm wafers with plasma polishing.	Ian Wright - Oxford Instruments
15 min	Coffee Break sponsored by Hakuto	
30 min	GaN PE/RF – Atomic Scale Processing <ul style="list-style-type: none">Production-qualified Plasma Atomic Layer Deposition for GaN HEMT passivation.Low damage, reliable etch processes for p-GaN HEMT and recessed MISHEMT manufacturing.	Dr Aileen O'Mahony - Oxford Instruments
20 min	Endpoint solutions <ul style="list-style-type: none">Leading endpoint accuracy.End pointing materials.	Dr Yuto Tomita - Laytec
10 min	Wrap up and next steps <ul style="list-style-type: none">Q&AFurther engagement.	Robert Gunn - Oxford Instruments
60 min	Happy hour	